

## Product Summary

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
-30V	95mΩ@-10V	-2A
	150mΩ@-4.5V	

## Feature

- Trench Power LV MOSFET technology
- Low  $R_{DS(on)}$  and FOM
- Extremely low switching loss
- Excellent stability and uniformity

## Application

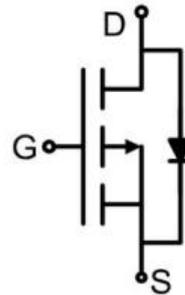
- Power management
- Portable equipment

## Package

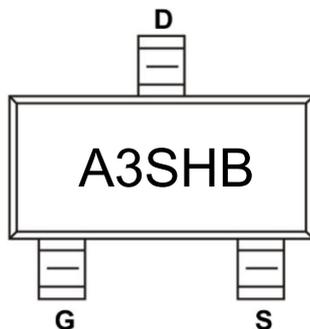


SOT-23

## Circuit diagram



## Marking



### Absolute maximum ratings ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-2	A
Continuous Drain Current( $T_A=100^\circ\text{C}$ )	$I_{D(100^\circ\text{C})}$	-1.3	A
Pulsed Drain Current <sup>1)</sup>	$I_{DM}$	-16	A
Power Dissipation <sup>2)</sup>	$P_D$	0.69	W
Thermal Resistance from Junction to Ambient <sup>3)</sup>	$R_{\theta JA}$	180	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55 ~ +150	$^\circ\text{C}$

### Electrical characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0\text{V}, I_D = -250\mu\text{A}$	-30			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}$			-1	$\mu\text{A}$
		$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, T_J = 150^\circ\text{C}$			-100	
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1.0	-1.5	-2.5	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = -10\text{V}, I_D = -2\text{A}$		71	95	m $\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -1\text{A}$		108	150	
<b>Dynamic characteristics<sup>4)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		190		pF
Output Capacitance	$C_{oss}$			34		
Reverse Transfer Capacitance	$C_{rss}$			26		
Gate Charge	$Q_g$	$V_{DS} = -15\text{V}, V_{GS} = -10\text{V}, I_D = -1\text{A}$		6.1		nC
Gate-Source Charge	$Q_{gs}$			1.3		
Gate-Drain Charge	$Q_{gd}$			1.2		
Gate resistance	$R_g$	$f = 1.0\text{MHz}$		25		$\Omega$
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -15\text{V}, V_{GS} = -10\text{V}, I_D = -1\text{A}, R_{GEN} = 3\Omega$		4		nS
Turn-on rise time	$t_r$			22		
Turn-off delay time	$t_{d(off)}$			20		
Turn-off fall time	$t_f$			27		
<b>Source-Drain Diode characteristics</b>						
Diode Forward Current	$I_S$				-2	A
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{V}, I_S = -2\text{A}$			-1.2	V
Reverse Recovery Charge	$Q_{rr}$	$I_F = -1\text{A}, di/dt = 100\text{A}/\mu\text{s}$		2.3		nC
Reverse Recovery Charge	$T_{rr}$			6		nS

Notes:

- 1) Repetitive rating; pulse width limited by max. junction temperature.
- 2)  $P_d$  is based on max. junction temperature, using junction-case and junction-ambient thermal resistance.
- 3) The value of  $R_{\theta JA}$  is measured with the device mounted on the minimum recommend pad size, in the still air environment with  $T_A = 25^\circ\text{C}$ . The maximum allowed junction temperature of  $150^\circ\text{C}$ . The value in any given application depends on the user's specific board design.
- 4) Guaranteed by design, not subject to production testing.

## Typical Characteristics

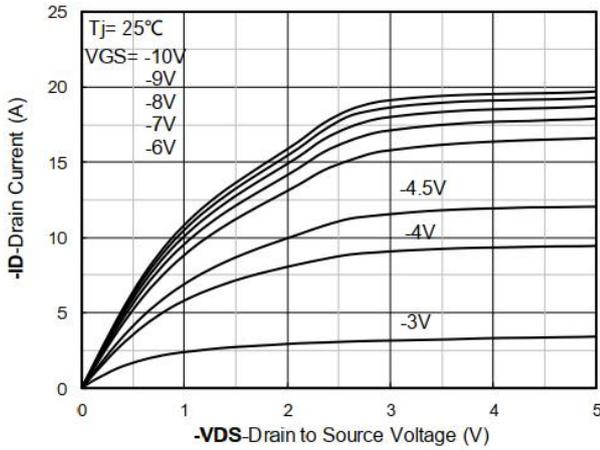


Figure 1. Output Characteristics

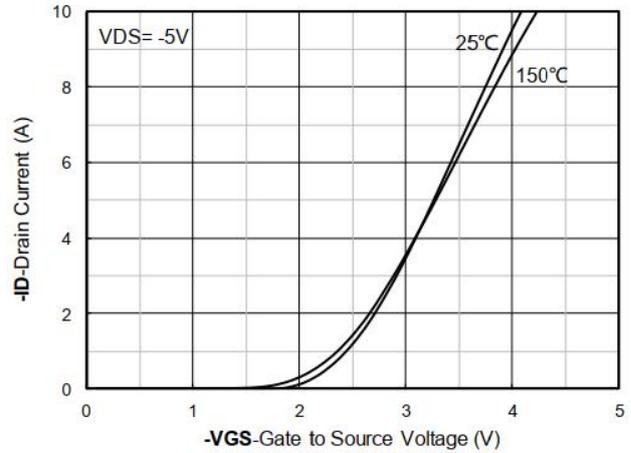


Figure 2. Transfer Characteristics

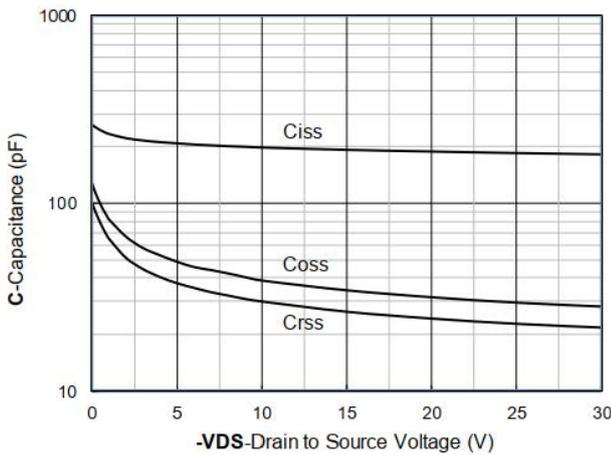


Figure 3. Capacitance Characteristics

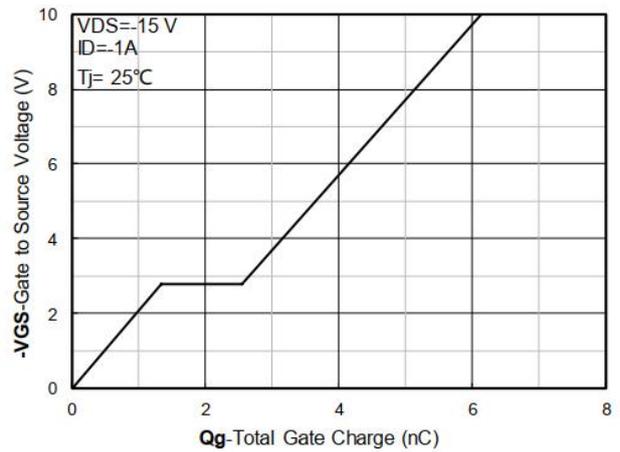


Figure 4. Gate Charge

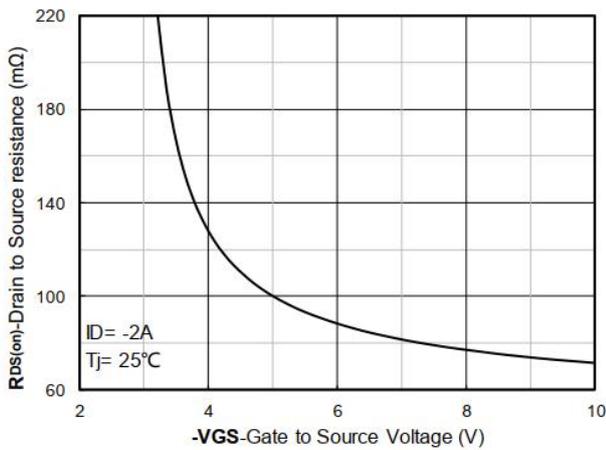


Figure 5. On-Resistance vs Gate to Source Voltage

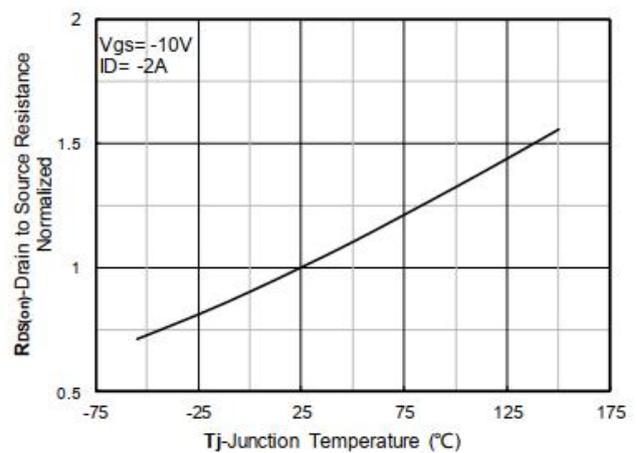


Figure 6. Normalized On-Resistance

## Typical Characteristics

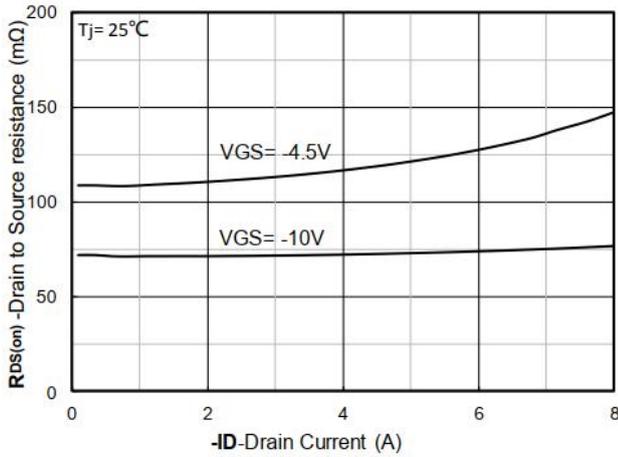


Figure 7. RDS(on) VS Drain Current

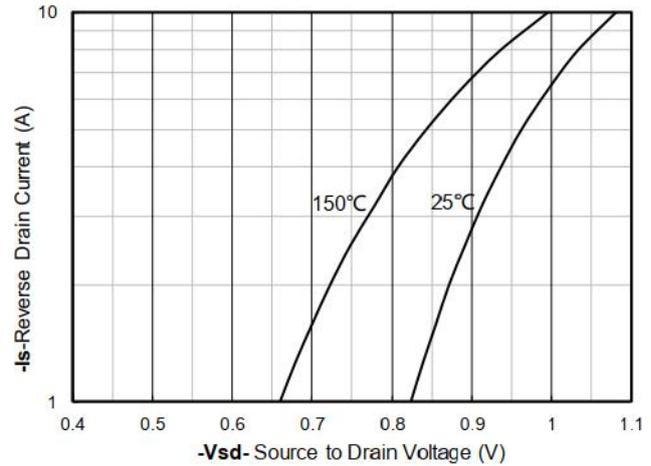


Figure 8. Forward characteristics of reverse diode

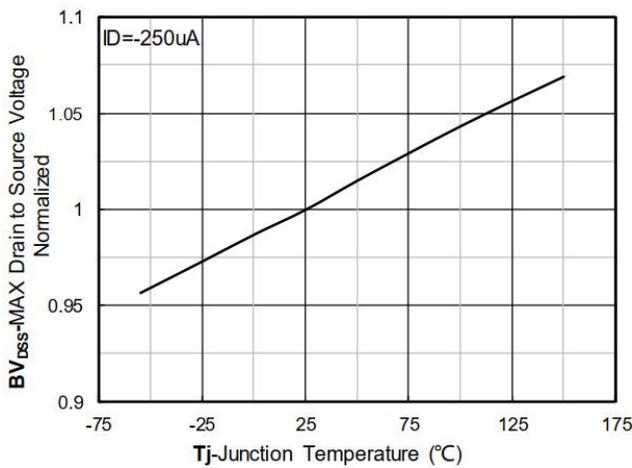


Figure 9. Normalized breakdown voltage

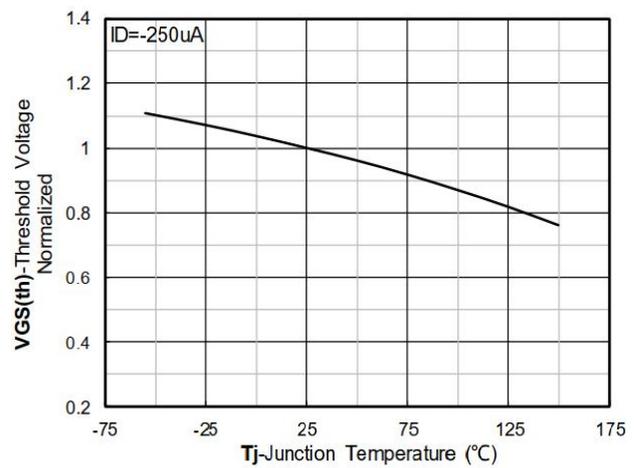


Figure 10. Normalized Threshold voltage

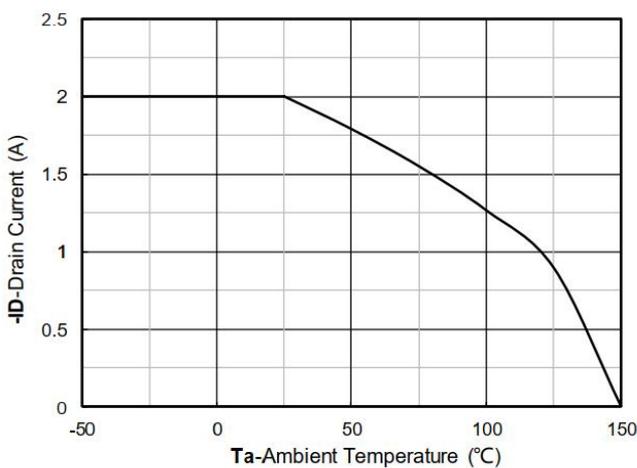


Figure 11. Current dissipation

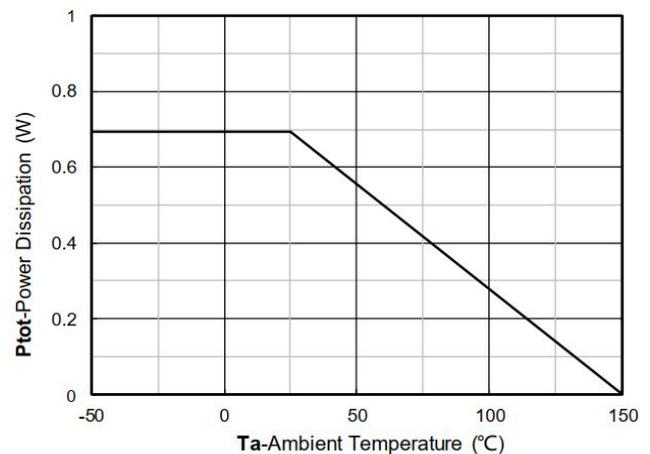


Figure 12. Power dissipation

## Typical Characteristics

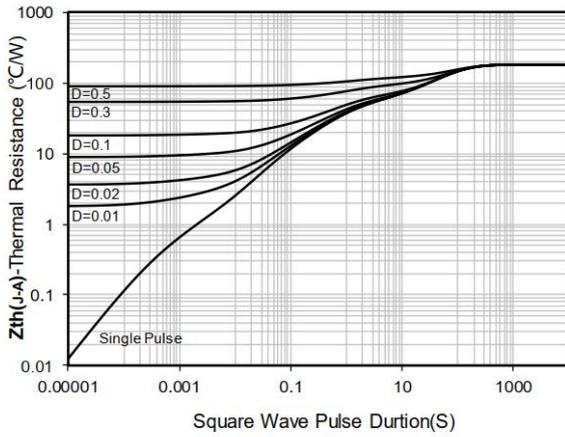


Figure 13. Maximum Transient Thermal Impedance

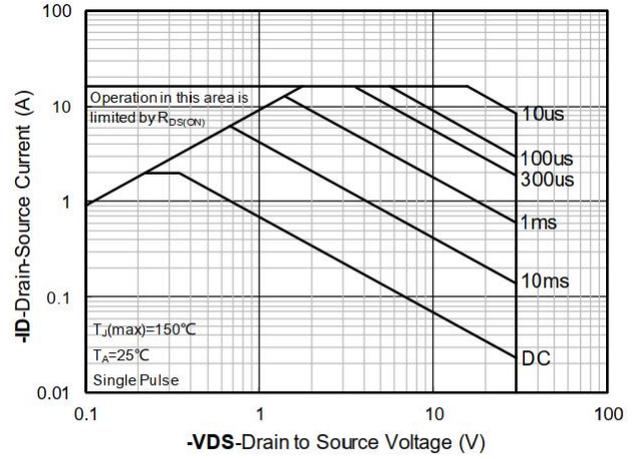
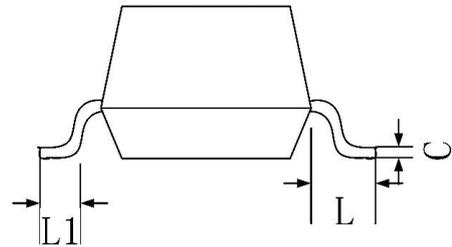
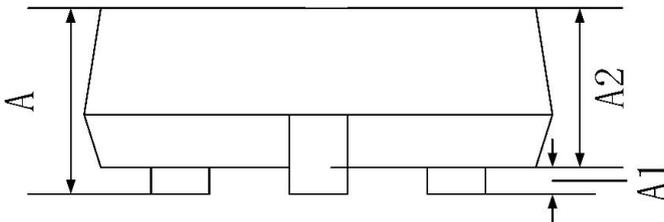
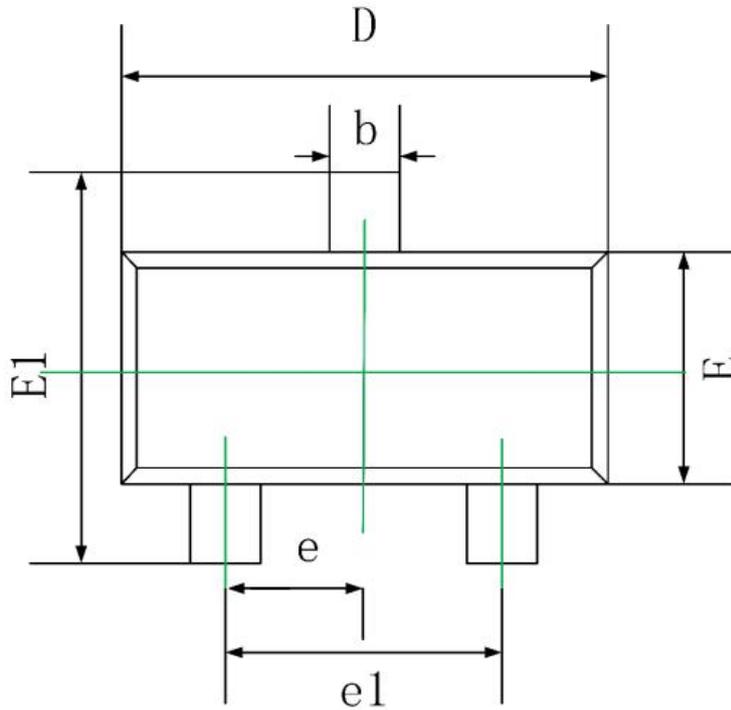


Figure 14. Safe Operation Area

## SOT-23 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.200	0.003	0.008
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP.		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF.		0.022 REF	
L1	0.300	0.500	0.012	0.020